

### **INVITATION TO PRESENT: FLEXIBLE PACKAGING**

Because India is one of the emerging leaders in the flexible packaging industry, the [2009 Flexible Packaging - Trends and Technology Developments Symposium](#) ([http://www.tappi.org/s\\_tappi/doc\\_events.asp?CID=11958&DID=562993](http://www.tappi.org/s_tappi/doc_events.asp?CID=11958&DID=562993)) will be held in India for the first time. The dual-located event will take place November 10-11, 2009 in Mumbai AND November 13-14, 2009 in New Delhi, India.

The symposium will be designed for professionals from all areas of the flexible packaging and converting industries. Abstracts are now being accepted on the following topics:

- New Trends in Flexible Packaging and Market Applications
- Retort and Aseptic Systems and Material Applications
- Environmental Issues and Recycling Technologies
- New Materials and Equipment Development

Authors interested in presenting at the symposium are invited to submit abstracts or technical papers to [IndiaPLACE@TAPPI.org](mailto:IndiaPLACE@TAPPI.org) by **June 30, 2009**. The Technical Program Committee will review all submissions in July and will respond to all authors shortly thereafter. The 2009 Flexible Packaging Symposium is co-hosted by TAPPI's PLACE Division; the Paper, Film & Foil Converters' Association; and The South Indian Education Society.